



**News Release**

5th December 2007

## **Tokyo Seimitsu supplies Rokko with Accretech PS280R Package Dicer.**

Tokyo Seimitsu Co., Ltd. (President and C.E.O.: Sadakatsu Suzuki) today announces that it has begun shipment of its new package singulation dicer model PS280R to Rokko Holdings Ltd., a precision engineering group listed on the Singapore Stock Exchange. The PS280R Package Dicer will be used by Rokko to deliver a fully automatic 'twin stages and twin tracks' package singulation solution to its customers through its newly developed Integrated Package Dicing, Pick and Place Systems Model: RS8000S. The newly developed technology has a potential 'cost of ownership'(COO) reduction of over 30% versus the conventional 'single stage and single track' package singulation solution for BGA and QFN products.

Tokyo Seimitsu announced the sale of the package singulation dicer "PS280" through a press release on August 10, 2007.

Tokyo Seimitsu has obtained 6 patents related to its package singulation dicing systems both in Japan and in the USA. In addition, it is applying for more than 10 patents specifically in the USA, Singapore, South Korea, Taiwan and other countries. With the supply of PS280R, Tokyo Seimitsu has agreed in principal to enter into a cross licensing agreement with Rokko Holdings.

### **About Rokko Holdings Ltd.**

Rokko is a precision engineering group listed in the Singapore Stock Exchange. It is principally engaged in the business of providing automated equipment and precision engineering services to customers in the semiconductor and electronics industries. It designs and manufactures proprietary semiconductor assembly equipment and precision tooling for use in the semiconductor industry, and also undertakes precision stamping of connectors for use in the electronics industry. It has over 180 employees world wide. Rokko is a supplier of automated equipment to providers of semiconductor assembly and test services such as United Test and Assembly Center Ltd, the Texas Instruments group of companies and Formosa Advanced Technologies Co., Ltd. The company was founded in 1994 and owns a portfolio of patents filed related to Integrated Package Dicing Solution.